

PLEASE CHECK WWW.MOLEX.COM FOR LATEST PART INFORMATION

Part Number:

0736443009

Status:

Active

Overview:

[hdm](#)

Description:

2.00mm (.079") Pitch HDM® Board-to-Board Backplane Header, Vertical, SMC, Press-Fit, Guide Post Location A, Polarizing Key Position E, 144 Circuits



Documents:

[Drawing \(PDF\)](#)

[RoHS Certificate of Compliance \(PDF\)](#)

Agency Certification

CSA

LR19980

UL

E29179

General

Product Family

Backplane Connectors

Series

73644

Application

Backplane

Comments

Standard Press-Fit, Tin/Lead (SnPb)

Component Type

PCB Header

Overview

[hdm](#)

Product Name

HDM®

Style

N/A

Physical

Circuits (Loaded)

144

Circuits (maximum)

144

Color - Resin

Black, Natural

Durability (mating cycles max)

250

First Mate / Last Break

No

Flammability

94V-0

Guide to Mating Part

Yes

Keying to Mating Part

Yes

Material - Metal

Phosphor Bronze, Stainless Steel

Material - Plating Mating

Gold

Material - Plating Termination

Tin

Material - Resin

High Temperature Thermoplastic

Number of Columns

24

Number of Pairs

Open Pin Field

Number of Rows

6

Orientation

Vertical

PC Tail Length (in)

0.138 In

PC Tail Length (mm)

3.50 mm

PCB Locator

No

PCB Retention

Yes

PCB Thickness Recommended (in)

0.098 In

PCB Thickness Recommended (mm)

2.50 mm

Packaging Type

Tube

Pitch - Mating Interface (in)

0.079 In

Pitch - Mating Interface (mm)

2.00 mm

Pitch - Term. Interface (in)

0.079 In

Pitch - Term. Interface (mm)

2.00 mm

Plating min: Mating (µin)

30

Plating min: Mating (µm)

0.75

Plating min: Termination (µin)

15

Plating min: Termination (µm)

0.375

Polarized to PCB

No

EU RoHS

China RoHS

Not RoHS Compliant

REACH SVHC

Not Reviewed

Halogen-Free

Status

Not Reviewed



Need more information on product environmental compliance?

Email productcompliance@molex.com
For a multiple part number RoHS Certificate of Compliance, [click here](#)

Please visit the [Contact Us](#) section for any non-product compliance questions.

Search Parts in this Series

73644Series

Mates With

73632 HDM PLUS® Board-to-Board Daughtercard Receptacle. 73780 HDM® Board-to-Board Daughtercard Receptacle

Application Tooling | FAQ

Tooling specifications and manuals are found by selecting the products below. Crimp Height Specifications are then contained in the Application Tooling Specification document.

Global	
Description	Product #
Flat Rock Tooling for	0622013700
Pneumatic Press	
HDM® Backplane	0621001400
Insertion Signal	
Contact Tool	
HDM® Backplane	0622005703
Insertion Head for	
144 Positions	
Extraction Tool	0621001000

Stackable	No
Surface Mount Compatible (SMC)	Yes
Temperature Range - Operating	-55°C to +105°C
Termination Interface: Style	Through Hole - Compliant Pin

Electrical

Current - Maximum per Contact	1A
Data Rate	1.0 Gbps
Real Signals (per 25mm)	75
Shielded	No
Voltage - Maximum	250V AC

Material Info

Reference - Drawing Numbers

Packaging Specification	PK-70873-0818
Sales Drawing	SDA-73644-****

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1. MATERIALS: HOUSING - LIQUID CRYSTAL POLYMER (LCP), GLASS-FILLED,
UL94V-0, COLOR: BLACK,
TERMINAL - PHOSPHOR BRONZE.

2. FINISHES: SELECTIVE GOLD (Au) IN CONTACT AREA, 0.00076mm MINIMUM
THICKNESS; NICKEL (Ni) AND GOLD FLASH OVERALL
SELECTIVE GOLD (Au) IN CONTACT AREA, 0.00076mm MIN.
THICKNESS; SELECTIVE TIN/LEAD (Sb/Pb) IN TAIL AREA;
NICKEL (Ni) OVERALL.

3. THIS PART CONFORMS TO MOLEX PRODUCT SPECIFICATION
PS-73670-9999.

4. FOR MIXED CONTACT MATING LENGTHS, CONSULT FACTORY FOR
AVAILABILITY.

5. DIMENSIONS ARE IN MILLIMETERS.

6. FOR SPECIFIC MATERIAL NUMBERS, REFER TO SHEET 2.

7. PACKAGE PER PK-70873-0818.

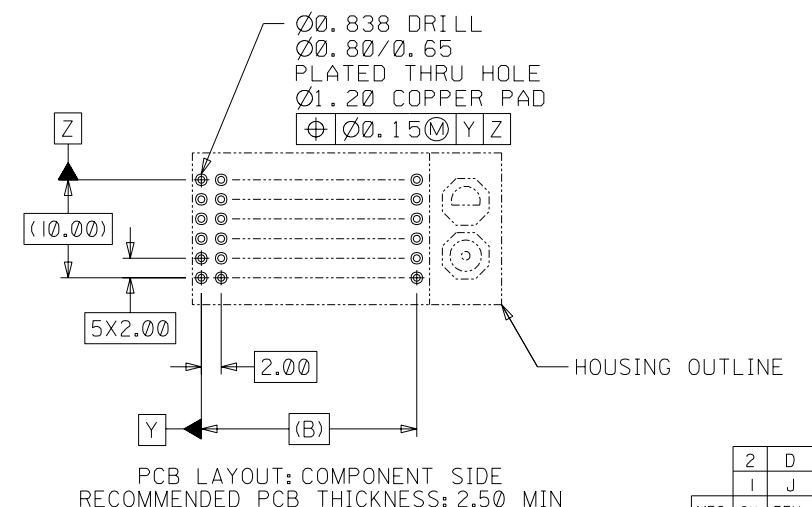
8. PARTS MARKED WITH PART NUMBER AND DATE CODE, ON EITHER SIDE,
APPROXIMATELY WHERE SHOWN.

The diagram shows the component side of a PCB layout. Key features include:
 - A central rectangular area labeled "HOUSING OUTLINE".
 - Dimensions: 11.7 mm total height, 3.5 mm bottom margin, 10.00 mm top margin, 5x2.00 mm contact area, 2.00 mm internal spacing, and 0.15 mm pad diameter.
 - Drill holes: Ø0.838 DRILL, Ø0.80/Ø.65 PLATED THRU HOLE, Ø1.20 COPPER PAD.
 - Pad dimensions: Ø0.15 mm.
 - Labels: Z, Y, B, (10.00), 5X2.00, 2.00, (B), Y.
 - Notes: (3.45) on the left margin.

PCB LAYOUT: COMPONENT SIDE
RECOMMENDED PCB THICKNESS: 2.50 MIN

REVISED JDT 2000-0348 HAM 99/10/12	DIMENSIONS SHOWN (METRIC) INCH UNLESS OTHERWISE SPECIFIED TOLERANCES: ANGULAR ± 1/2°	TITLE SALES ASSY, HDM BACKPLANE MODULE, POLAR/GUIDE OPTION	PART NO. SEE CHART
REVISED JDT 1999-0662 HAM 99/05/18	INCH METRIC 3 PLACE ± N/A --- 2 PLACE ± N/A ± 0.05 1 PLACE --- ± 0.10	MOLEX INCORPORATED LISLE, ILL. 60532 U.S.A.	SHEET NO. 1 OF 2 DATE 96/12/18
REVISED JDT 1999-0476 HAM 98/12/21	DRAWING WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	DIV. DA	SIZE B
APP'D. BY CAB	CHK'D. BY SMR SCALE 2 : 1	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INC. AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION.	

MFG.	SH.	REV.	2 D 1 J
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				I	REVISED ECR UDT2000-0348 BINGHAM 99/10/12	DIMENSIONS SHOWN (METRIC) INCH UNLESS OTHERWISE SPECIFIED TOLERANCES: ANGULAR ± 1/2° <table><tr><td></td><td>INCH</td><td>METRIC</td></tr><tr><td>3 PLACE</td><td>± N/A</td><td>---</td></tr><tr><td>2 PLACE</td><td>± N/A</td><td>± 0.05</td></tr><tr><td>1 PLACE</td><td>---</td><td>± 0.10</td></tr></table> DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS			INCH	METRIC	3 PLACE	± N/A	---	2 PLACE	± N/A	± 0.05	1 PLACE	---	± 0.10	▽ = 0 ▼ = 0 REVISE ONLY ON CAD SYSTEM	
	INCH	METRIC																			
3 PLACE	± N/A	---																			
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1 PLACE	---	± 0.10																			
				H	REVISED ECR UDT1999-0662 BINGHAM 99/05/18			TITLE SALES ASSY, HDM BACKPLANE MODULE, POLAR/GUIDE OPTION													
J		REVISED ECR UCP2003-2260 THOMAS 03/04/25	G	REVISED ECR UDT1999-0476 BINGHAM 98/12/21			molex MOLEX INCORPORATED LISLE, ILL. 60532 U.S.A.		SHEET NO. 1 OF 2	DATE 96/12/18											
						DRWG. BY JRR	CHK'D. BY SMR	PART NO. SEE CHART		DRWG. NO. SDA-73644-****											
LTR.		REVISIONS	LTR.	REVISIONS		APP'D. BY CAB	SCALE 2 : 1	FILE NAME S73644X1 DGN		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INC. AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION.	DIV. DA	SIZE B									

Компания «Life Electronics» занимается поставками электронных компонентов импортного и отечественного производства от производителей и со складов крупных дистрибьюторов Европы, Америки и Азии.

С конца 2013 года компания активно расширяет линейку поставок компонентов по направлению коаксиальный кабель, кварцевые генераторы и конденсаторы (керамические, пленочные, электролитические), за счёт заключения дистрибьюторских договоров

Мы предлагаем:

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- Специальные условия для постоянных клиентов.
- Подбор аналогов.
- Поставку компонентов в любых объемах, удовлетворяющих вашим потребностям.
- Приемлемые сроки поставки, возможна ускоренная поставка.
- Доставку товара в любую точку России и стран СНГ.
- Комплексную поставку.
- Работу по проектам и поставку образцов.
- Формирование склада под заказчика.
- Сертификаты соответствия на поставляемую продукцию (по желанию клиента).
- Тестирование поставляемой продукции.
- Поставку компонентов, требующих военную и космическую приемку.
- Входной контроль качества.
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- Регистрацию проекта у производителя компонентов.
- Техническую поддержку проекта.
- Защиту от снятия компонента с производства.
- Оценку стоимости проекта по компонентам.
- Изготовление тестовой платы монтаж и пусконаладочные работы.



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